SUPPORT FOR THE AMENDMENT

The Preliminary Amendment filed October 25, 2005 (copy attached, along with date-stamped filing receipt), canceled Claims 1-14 and added Claims 15-42.

This Amendment cancels Claims 15-42; and adds new Claims 43-59. Support for the amendments is found in the specification and claims as originally filed. It is believed that no new matter would be introduced by entry of these amendments.

Upon entry of these amendments, Claims 43-59 will be pending in this application. Claims 43, 44, 45 and 47 are independent.

REQUEST FOR RECONSIDERATION

Applicants respectfully request entry of the foregoing and reexamination and reconsideration of the application, as amended, in light of the remarks that follow.

The present invention provides a material for purification of a semiconductor polishing slurry.

Claims 1-4 are rejected under 35 U.S.C. §103(a) over EP 1179627 ("Nambu"). Claims 1-4 were canceled in the Preliminary Amendment filed October 25, 2005, so the rejection is moot and should be withdrawn.

Pending Claims 43-59 are patentable over Nambu.

Nambu discloses a fiber capable of forming a metal chelate, where the fiber is characterized in that at least one metal chelate-forming compound selected from the group consisting of aminodicarboxylic acids, aminocarboxylic acids, thiocarboxylic acids and phosphoric acid, which are reactive with a glycidyl group, is bonded to a molecule of a natural fiber or regenerated fiber through a crosslinkable compound having a reactive double bond and a glycidyl group in its molecule. Nambu at abstract. Nambu also discloses a method of using the fiber to capture metal ions contained in trace amounts in an aqueous or

oily liquid or in a gas. Nambu at abstract; [0009]. Nambu discloses that the metal chelate-forming fiber is capable of selectively adsorbing metal ions in trace amounts, for example, in water, especially copper, zinc, cobalt and other heavy metal ions and can be used in the purification of industrial waste water, drinking water and oil. Nambu at [0001].

However, Nambu does not disclose a material suitable for purification of a semiconductor polishing slurry. The material disclosed by Nambu merely removes heavy metals from industrial wastewater not to trace order, and disposes the industrial water as waste after removing heavy metals.

According to the invention of independent Claim 43, a material for purification of a semiconductor polishing slurry has a functional group capable of forming a metal chelate which "is at least one group selected from a group containing aminocarboxylic acids, a group containing phosphoric acids, a group containing thio compounds and at least a part of acid type functional groups of these groups determined as an acid type (H type)". Also the material for purification of a semiconductor polishing slurry in Claim 43 is used for purification of an acidic semiconductor slurry.

According to the invention of independent Claim 44, a material for purification of a semiconductor polishing slurry has a functional group capable of forming a metal chelate which "is at least one group selected from a group containing aminocarboxylic acids, a group containing phosphoric acids, a group containing thio compounds and at least a part of acid type functional groups of these groups determined as alkali metal salt or ammonium salt", and is used for purification of a basic semiconductor polishing slurry.

The materials described in each of independent Claims 43-44 can remove metals in a semiconductor polishing slurry to trace order. Thus, the materials described in each of Claims 43-44 are suitable for purification of a semiconductor polishing slurry. However, Nambu does not disclose the materials described in independent Claims 43-44. The material

disclosed by Nambu merely removes heavy metals from industrial wastewater not to trace order, and disposes the industrial water as waste after removing heavy metals. On the other hand, since the materials in Claims 43-44 can remove metals to trace order, the semiconductor polishing slurry, after removing metals, can be reused.

Nambu also fails to disclose or suggest the process for purification of a semiconductor polishing slurry of either of Claims 45 and 47. As discussed above, Nambu disposes industrial water as waste after removing heavy metals. In contrast, the invention of independent Claim 45 is a process for purification of a semiconductor polishing slurry, and ***reuse*** of the semiconductor polishing slurry after removing metals. The invention of independent Claim 47 is also a process for purification of a semiconductor polishing slurry, and ***reuse*** of the semiconductor polishing slurry after removing metals.

Nambu also fails to disclose or suggest the combination of features of each of Claims 46 and 48-59.

Because Nambu fails to disclose or suggest all the limitations of the claimed invention, Claims 43-59 are patentable over Nambu.

Claims 5-14 are objected to under 37 C.F.R. §1.75(c) as being in improper form because a multiple dependent claim cannot depend from another multiple dependent claim. In addition, Claim 4 is objected to under 35 U.S.C. §112, second paragraph. Claims 4 and 5-14 were canceled in the Preliminary Amendment filed October 25, 2005, so the rejections are moot and should be withdrawn.

In view of the foregoing amendments and remarks, Applicants respectfully submit that the application is in condition for allowance. Applicants respectfully request favorable consideration and prompt allowance of the application.

Should the Examiner believe that anything further is necessary in order to place the application in even better condition for allowance, the Examiner is invited to contact Applicants' undersigned attorney at the telephone number listed below.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.
Norman F. Oblon

Corwin P. Umbach, Ph.D.
Registration No. 40,211

Customer Number
22850

Tel: (703) 413-3000
Fax: (703) 413 -2220
(OSMMN 08/07)

Attached:
Preliminary Amendment filed October 25, 2005, with date-stamped filing receipt